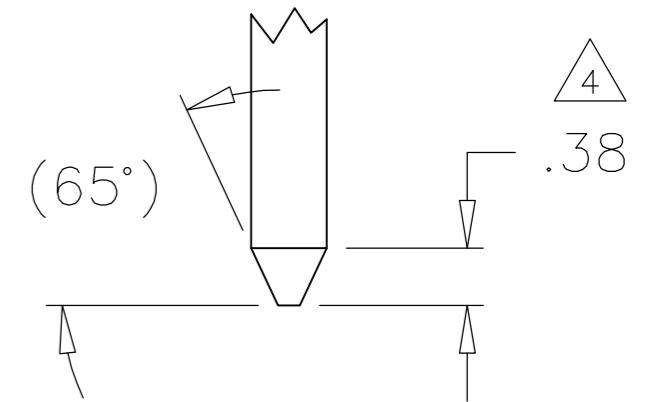
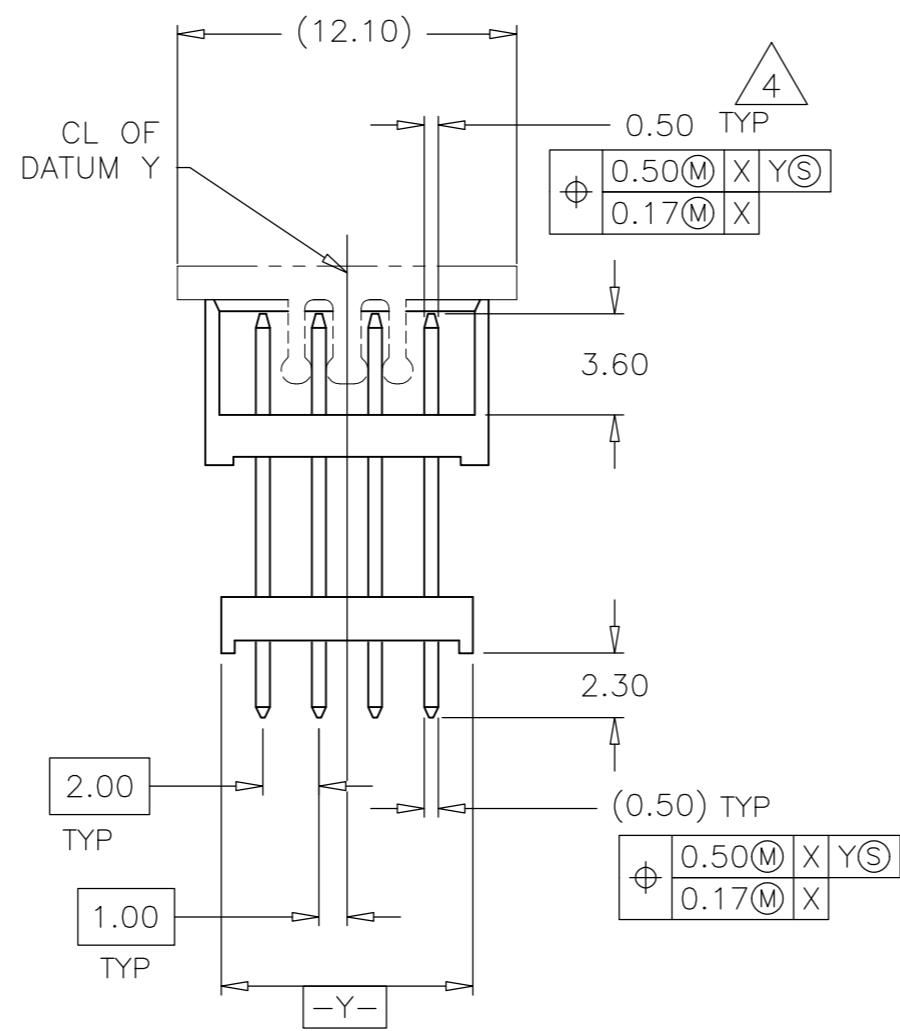
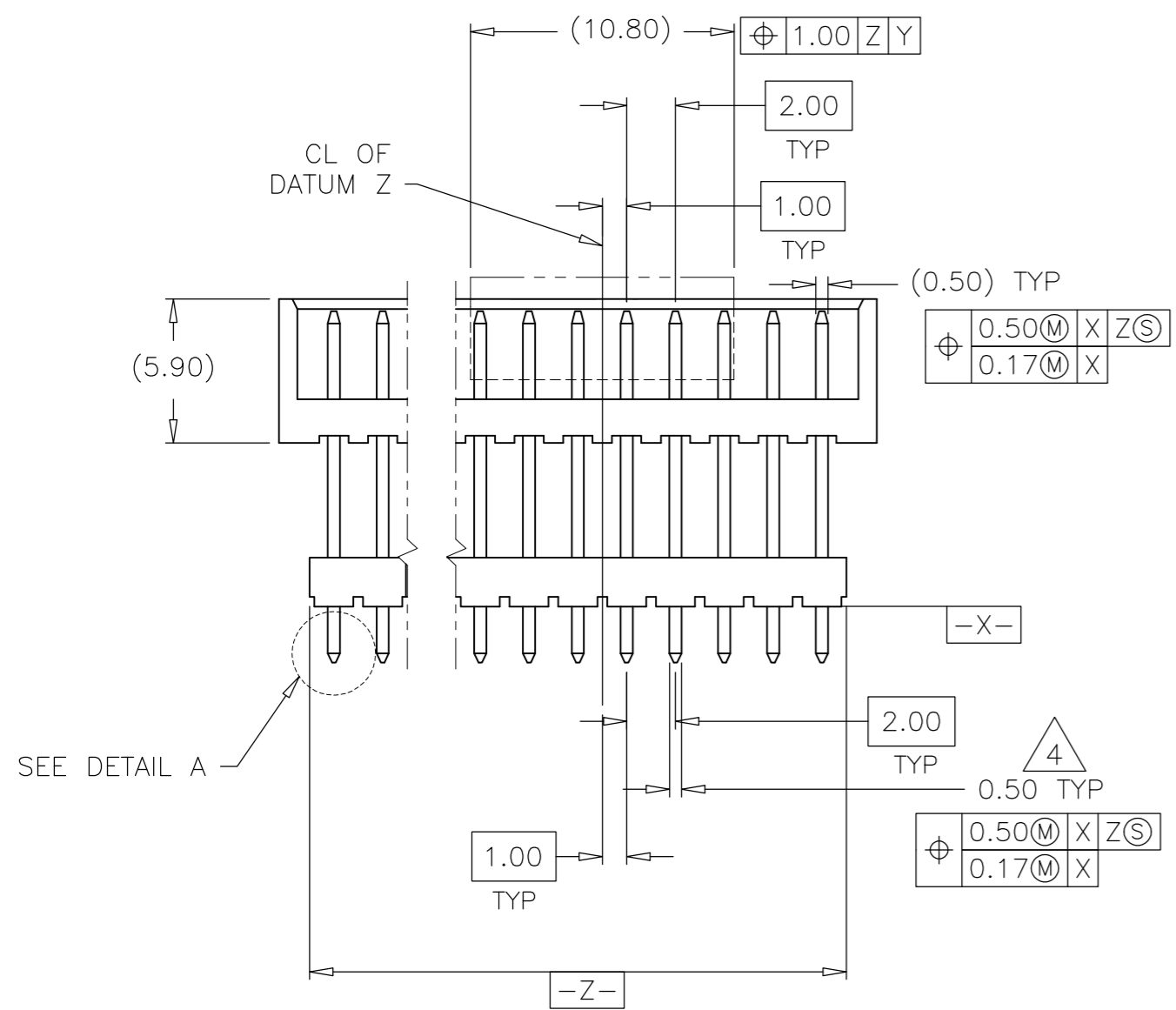
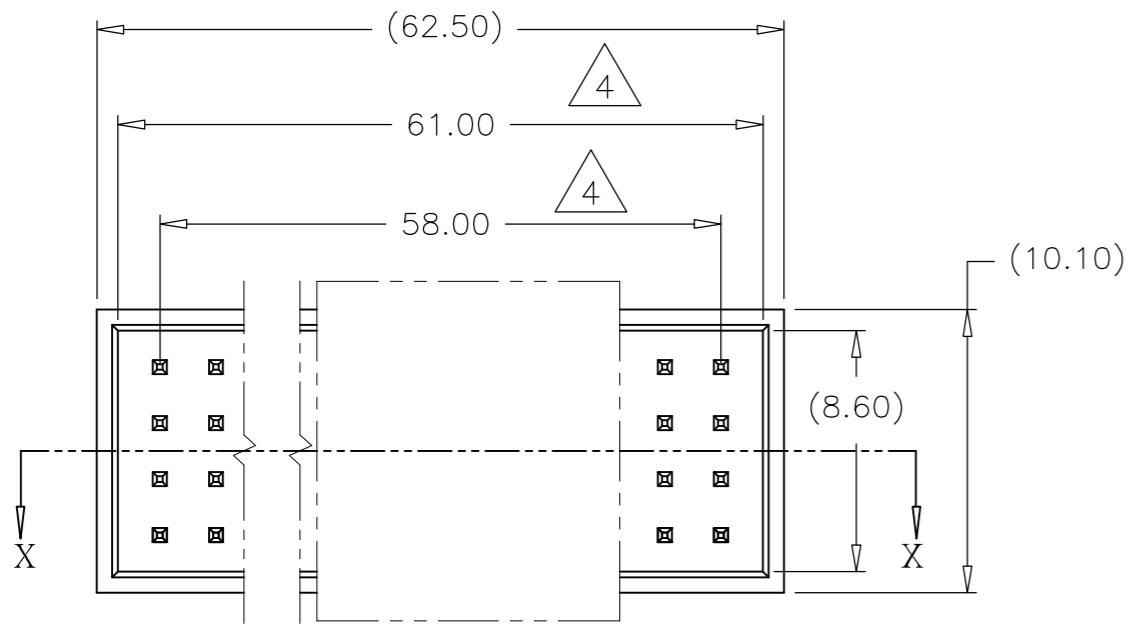
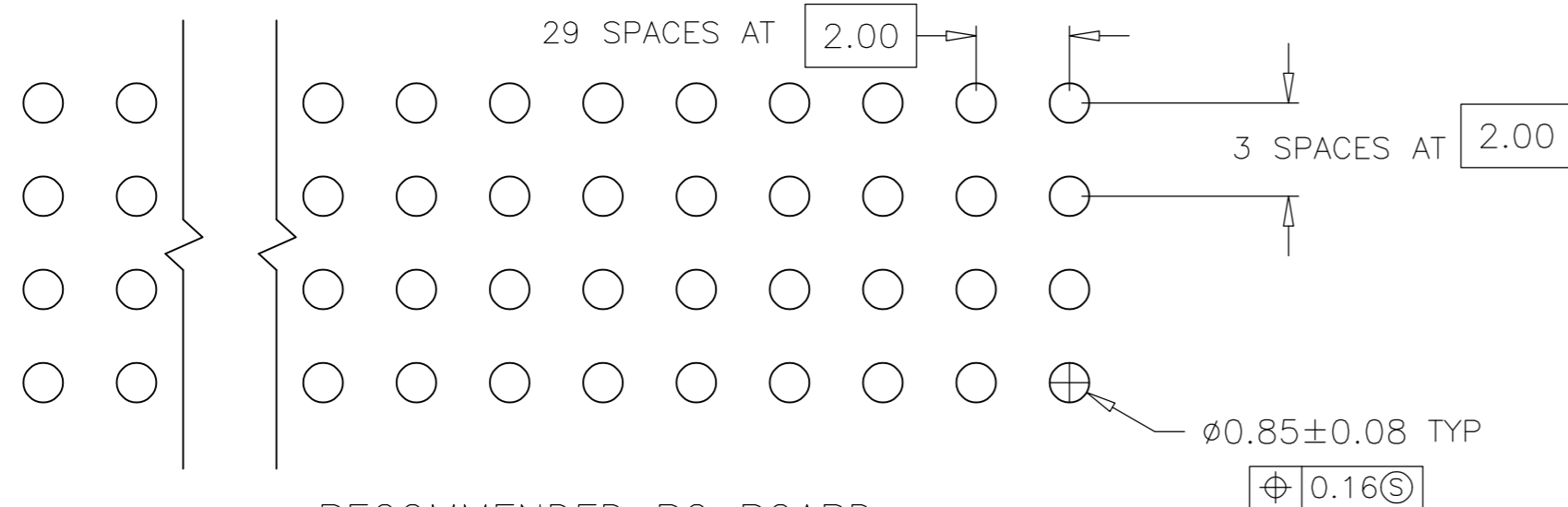


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LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
AD	00						
	K	REVISED PER ECO-11-012012	29AUG11	HMR	JO		



DETAIL A
SCALE: 3:1



RECOMMENDED PC BOARD HOLE LAYOUT

TOLERANCES NOT TO ACCUMULATE WITHIN ONE CONNECTOR PATTERN.

1. SPECIFICATIONS-

CONTACT MATERIAL: PHOSPHOR BRONZE,
 VACUUM CAP & INSULATOR MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, LCP

PACKAGING: TAPE AND REEL PER EIA-481

- 2 CONTACT FINISH: DUPLEX PLATED 0.000762 GOLD ON CONTACT AREA, TIN-LEAD ON SOLDER LEADS
- 3 CONTACT FINISH: DUPLEX PLATED 0.000762 GOLD ON CONTACT AREA, 0.00381 TIN ON SOLER LEADS 0.00127 NICKEL UNDERPLATING
- 4 CRITICAL TO QUALITY

SUPERSEDED BY 5-1571556-1

3	120	5-1571556-1
2	120	1571556-1
FINISH	NO OF POSN	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN R BROWN 18MAR04	STE TE Connectivity	
DIMENSIONS: mm		CHK D SIMPSON 18MAR04	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD D SIMPAON 18MAR04	PRODUCT SPEC	
0 PLC ± -		108-2273-1		SIZE
1 PLC ± 0.25		APPLICATION SPEC		CAGE CODE
2 PLC ± 0.25		114-13177		DRAWING NO
3 PLC ± -		WEIGHT -		RESTRICTED TO
4 PLC ± -		CUSTOMER DRAWING		SCALE 1:1
ANGLES ± 4°		FINISH -		SHEET 1 of 1
MATERIAL -		A2 00779 C=1571556		REV K

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)